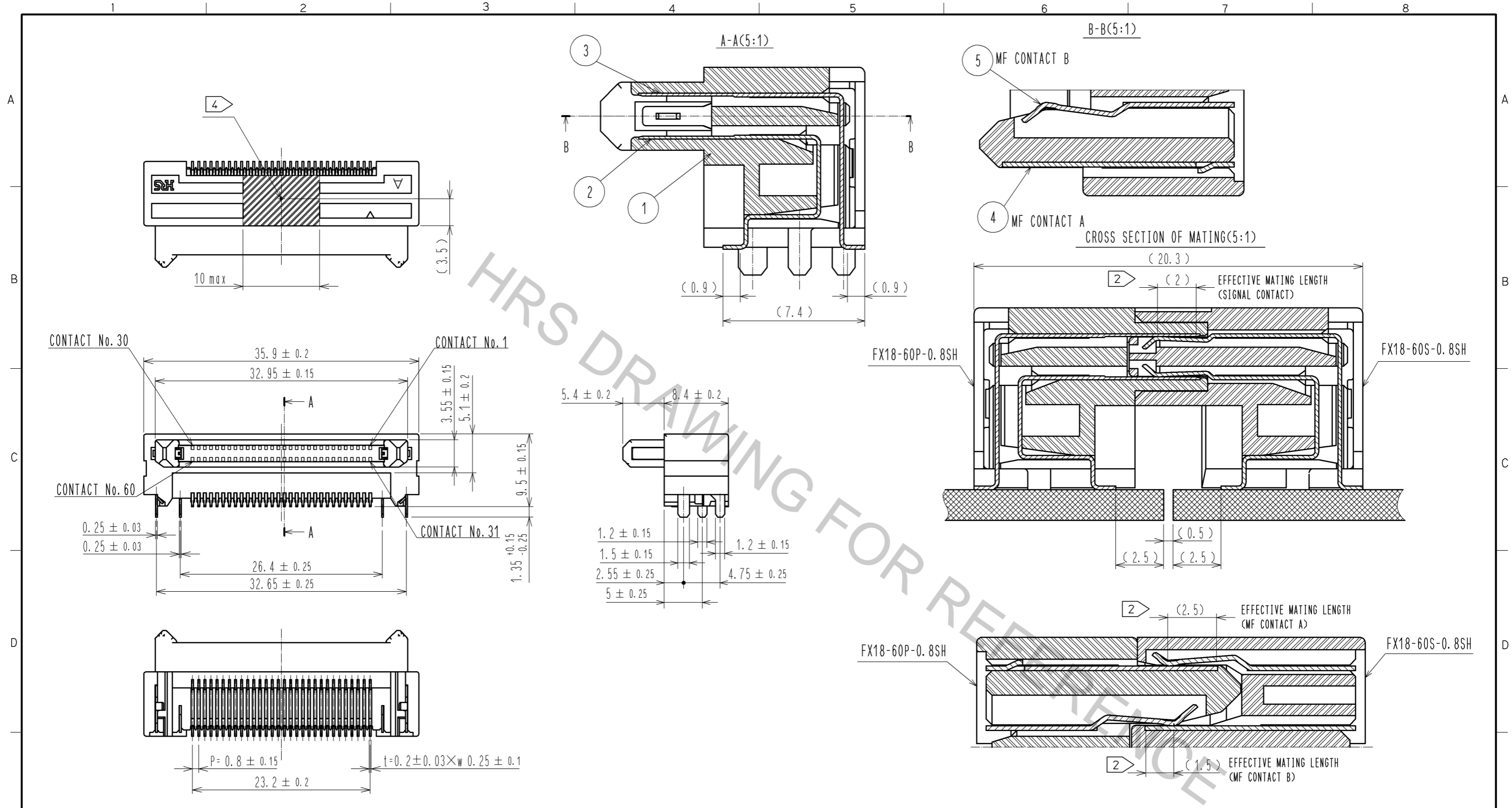


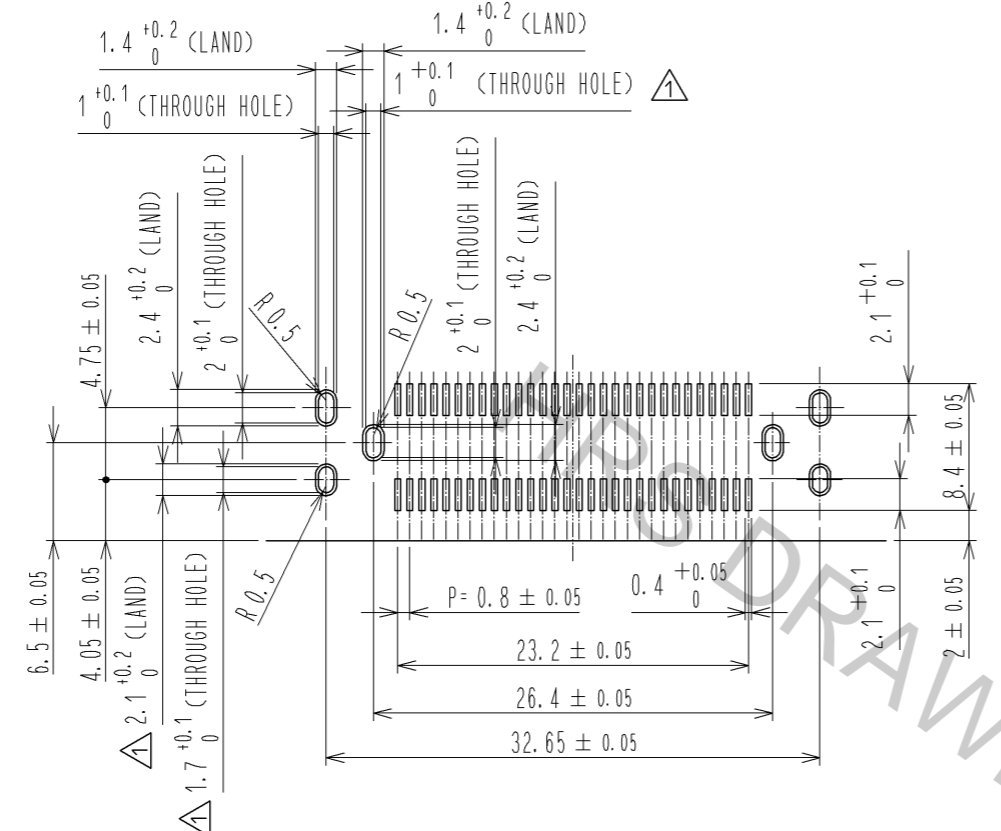
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NOTE 1 LEAD CO-PLANARITY IS 0.1mm MAX.
 ② CONTACTS ARE 3 STEPS SEQUENTIAL. (MF CONTACT A->SIGNAL CONTACT->MF CONTACT B) WHEN USING THIS SEQUENTIAL STRUCTURE, PLEASE AVOID ANGLED INSERTION.
 3 MF CONTACT A AND MF CONTACT B CAN BE USED AS POWER SUPPLY CONTACT. (3A/PIN MAX)
 ④ IT SHOWS CONNECTOR'S CENTRE OF GRAVITY AND VACUUM PICKUP AREA.
 ⑤ THIS IS PACKAGED IN TRAY. (60pcs/TRAY)
 6 BLEMISH AND HIT MARK CAN BE OCCURED THROUGH OUT THE MANUFACTURING PROCESS WHICH DOESN' T AFFECT QUALITY LEVEL.
 7 THE DIMENSIONS IN PARENTHESES ARE FOR REFERENCES.

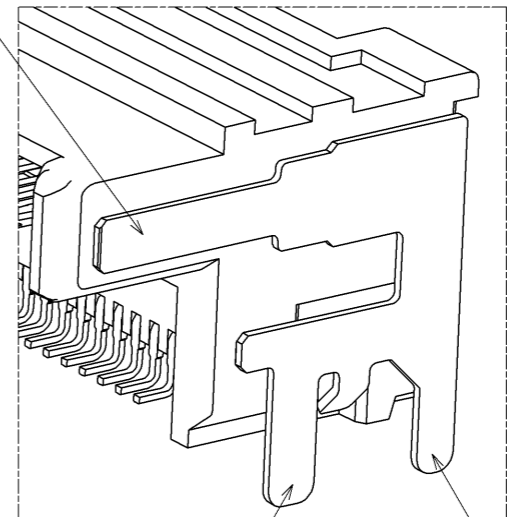
3	PHOSPHOR BRONZE	CONTACT AREA:GOLD 0.1µm LEAD AREA:GOLD 0.03µm UNDER PLATING:NICKEL 1.3µm	6	POLYSTYRENE	
2	PHOSPHOR BRONZE	CONTACT AREA:GOLD 0.1µm LEAD AREA:GOLD 0.03µm UNDER PLATING:NICKEL 1.3µm	5	PHOSPHOR BRONZE	CONTACT AREA:GOLD 0.1µm LEAD AREA:TIN-PLATING 1µm UNDER PLATING:NICKEL 1.3µm
1	POLYAMIDE	BLACK UL94V-0	4	PHOSPHOR BRONZE	CONTACT AREA:GOLD 0.1µm LEAD AREA:TIN-PLATING 1µm UNDER PLATING:NICKEL 1.3µm
NO.	MATERIAL	FINISH . REMARKS	NO.	MATERIAL	FINISH . REMARKS
UNITS mm		SCALE 2 : 1	COUNT 4	DESCRIPTION OF REVISIONS DIS-F-005578	
DESIGNED TH. SANO		CHECKED KI. HIROKAWA		DATE 11.07.21	
APPROVED : HS. OKAWA 09.10.09		DRAWING NO. EDC3-159075-00			
CHECED : KI. HIROKAWA 09.10.09		PART NO. FX18-60P-0.8SH			
DESIGNED : TH. SANO 09.10.09		CODE NO. CL579-0003-8-00			
DRAWN : TH. SANO 09.10.09					

RECOMMENDED LAND PATTERN DIMENSION OF PCB(2:1)
 (PCB THICKNESS:t=1.6mm, METAL MASK THICKNESS:t=0.12mm)



8 CONFIGURATION OF MF CONTACT A

CONTACT AREA OF MF CONTACT A

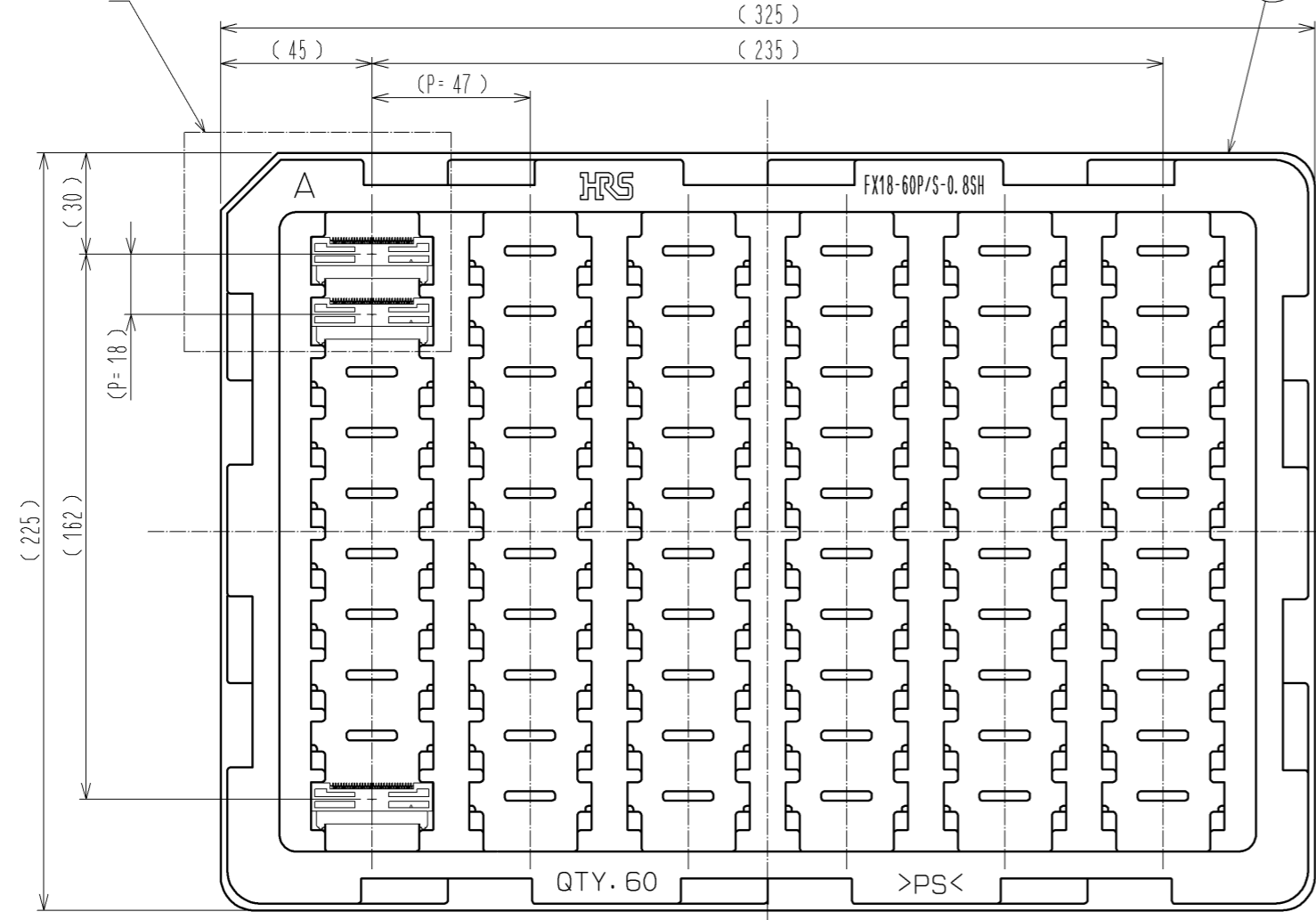


SOLDERING POLE2 OF MF CONTACT A

SOLDERING POLE1 OF MF CONTACT A

NOTE 8 SOLDERING LEAD OF MF CONTACT A SPLITS INTO TWO POLES.
 BE SURE TO CONNECT TO THE SAME CIRCUIT.

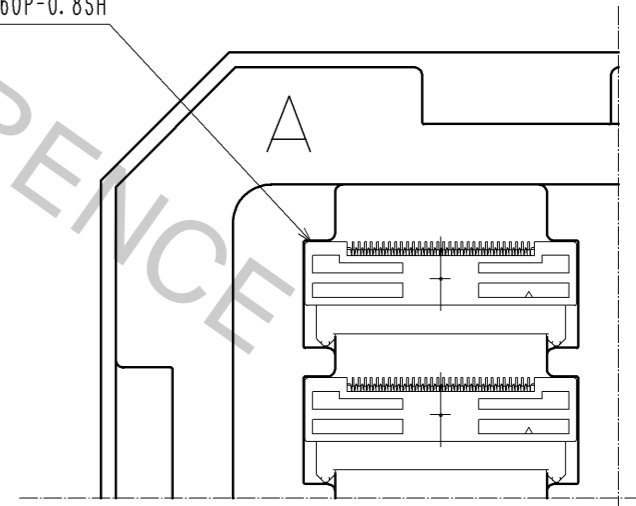
5 DRAWING FOR PACKING(1:2)



(18)

C(1:1)

FX18-60P-0.8SH



DRAWING NO.	EDC3-159075-00
PART NO.	FX18-60P-0.8SH
CODE NO.	CL579-0003-8-00